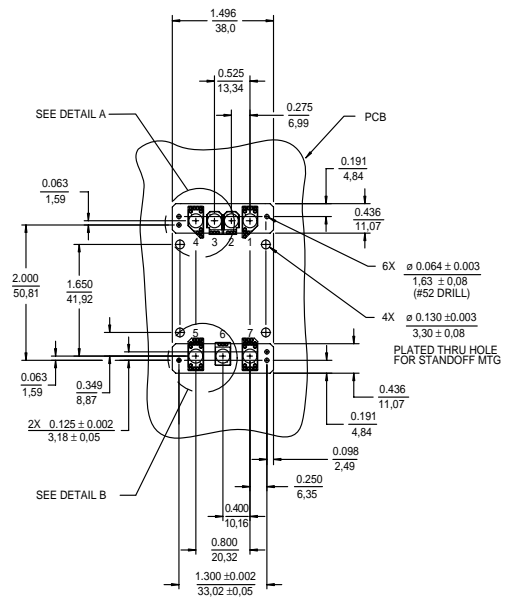
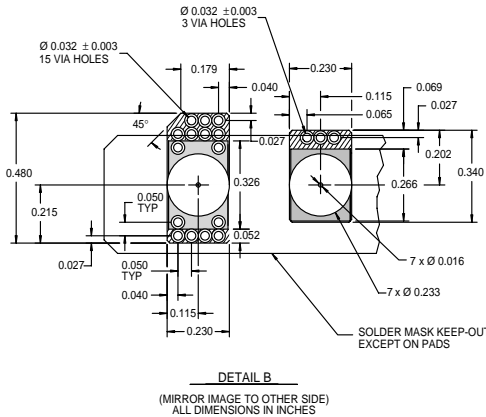
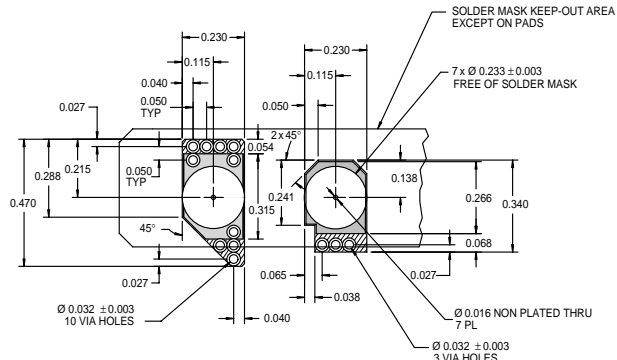
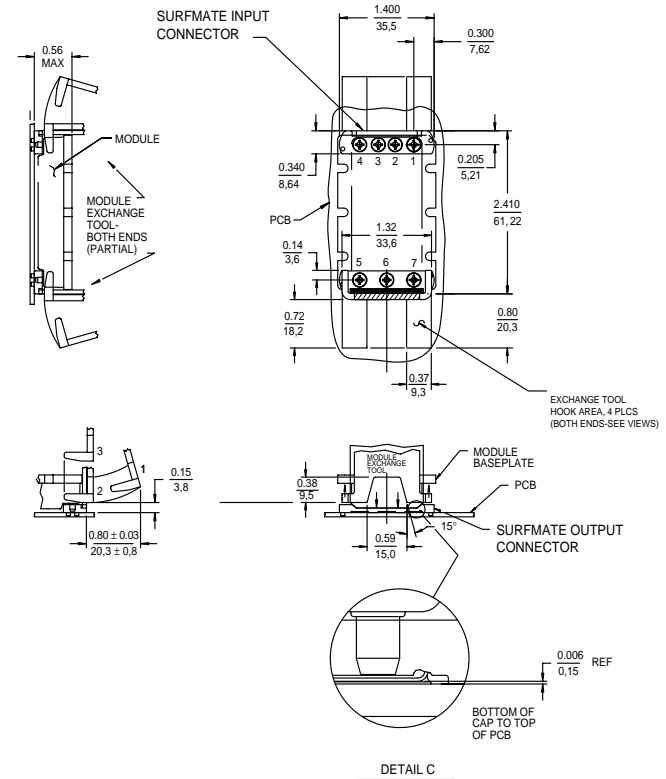


PCB Layout Drawing for Micro Size Module

W W W . V I C T O R . C O M



PIN LEGEND					
Pin Number	Micro		VI-ARM		Pin Dia. (Inches / mm)
	Symbol	Function	Symbol	Function	
1	+	+IN	-V	-Out	0.080 / 2,03
2	PC	Prim. Control	EN	Enable	0.080 / 2,03
3	PR	Parallel	B OK	-Bus OK	0.080 / 2,03
4	-	-IN	+V	+Out	0.080 / 2,03
5	-	-OUT	N	Neutral	0.150 / 3,81
6	SC	Sec. Control	ST	Strap	0.080 / 2,03
7	+	+OUT	L	Line	0.080 / 2,03



All dimensions are **Inch** or **Inch / Metric**
ANSI / IPC-D-300 specifications apply for Class "B" boards.
Recommended PCB construction:

Multilayer 3oz Cu with internal power and ground planes. Pad geometry and minimum number of via holes for connection to power and ground planes shown in Details "A" & "B" for high current applications. Pads to be covered with solder mask except in circular area shown in Detail "A" & "B". Final pad height above laminate to be 0.004" +/- 0.0004".

Light gray area denotes stencil aperture (should include circular solder mask keep-out area on each pad).

PRODUCT APPLICATION SPECIFICATIONS